



Innovative Interconnections™

**For Immediate Release**

**Autosplice Solderball Pin Technology  
Receives VISION Award  
Presented at IPC APEX**

San Diego, CA - - Autosplice's innovative Solderball Pin™ applied technology received the VISION Award for outstanding achievement in the Packages-Connectors category. The award was accepted for Autosplice by Carlos Juvera, Global Product Manager, during the 16th Annual VISION Awards Ceremony at Mandalay Bay Resort & Convention Center, Las Vegas on April 2, 2008, during IPC APEX.

Solderball Pin technology employs a highly conductive copper pin that incorporates a solder ball on the end that interfaces to the host PCB. Solderball pins add two important attributes to final assembly by providing additional solder and allowing the sub-assembly to drop slightly when the solder becomes liquid. This drop occurs when the weight of the module overcomes the buoyancy of the molten solder. It is made possible by the fact that the bottom end of the pin extends only part way into the solder ball. Therefore Solderball Pin technology is able to automatically align and compensate for PCB co-planarity variances up to 0.020" during the solder reflow process.

The inherent design flexibility of Solderball Pin technology allows designers of PCB-based modules to determine optimal patterns and positioning of individual interconnects, thereby allowing design and layout consistency between new SMT versions and through-hole versions, which allows a smooth roadmap of evolutionary product offerings and surface mountable product options.

The use of Solderball Pin technology also leverages existing automation equipment and assembly methods while giving module designers a high degree of flexibility to optimize interconnect patterns and circuit layout. This enables a smooth technology roadmap for migrating existing through-hole designs to surface mount versions and streamlines the assembly process for module designers, OEMs and contract manufacturers.

Solderball Pin technology is the preferred cost-effective SMT interconnection method in point-of-load power applications of major DC/DC conversion power electronics OEMs. Solderball Pin technology's compact configuration and flexibility as a discrete SMT component facilitates adoption into a broad scope of different applications, including electronic lighting controls, remote telemetry monitoring, Ethernet, fiber channel, storage area networks, automotive, and many other daughter-to-motherboard module-based subassemblies.

Autosplice is a leading manufacturer of terminals, component assemblies and applicator systems, providing automated solutions for high-volume electrical interconnections. Autosplice systems enable substantial cost savings and provide superior reliability over conventional connector products and assembly methods.

**For More Information:**

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